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Summary of Conference of Science & Technology for Integrated Circuits（CSTIC） 2024

March 17-18, 2024

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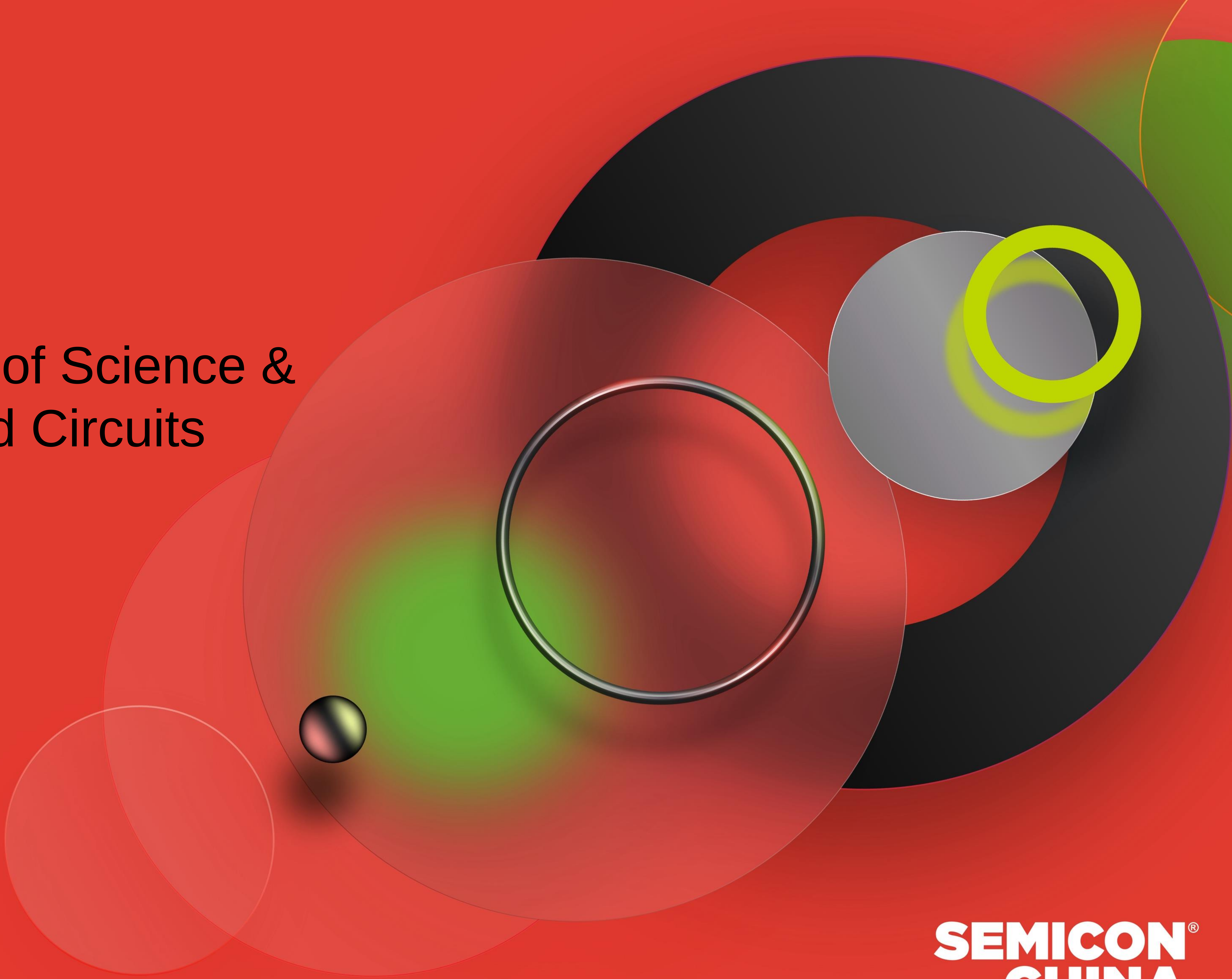

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CSTIC 2024

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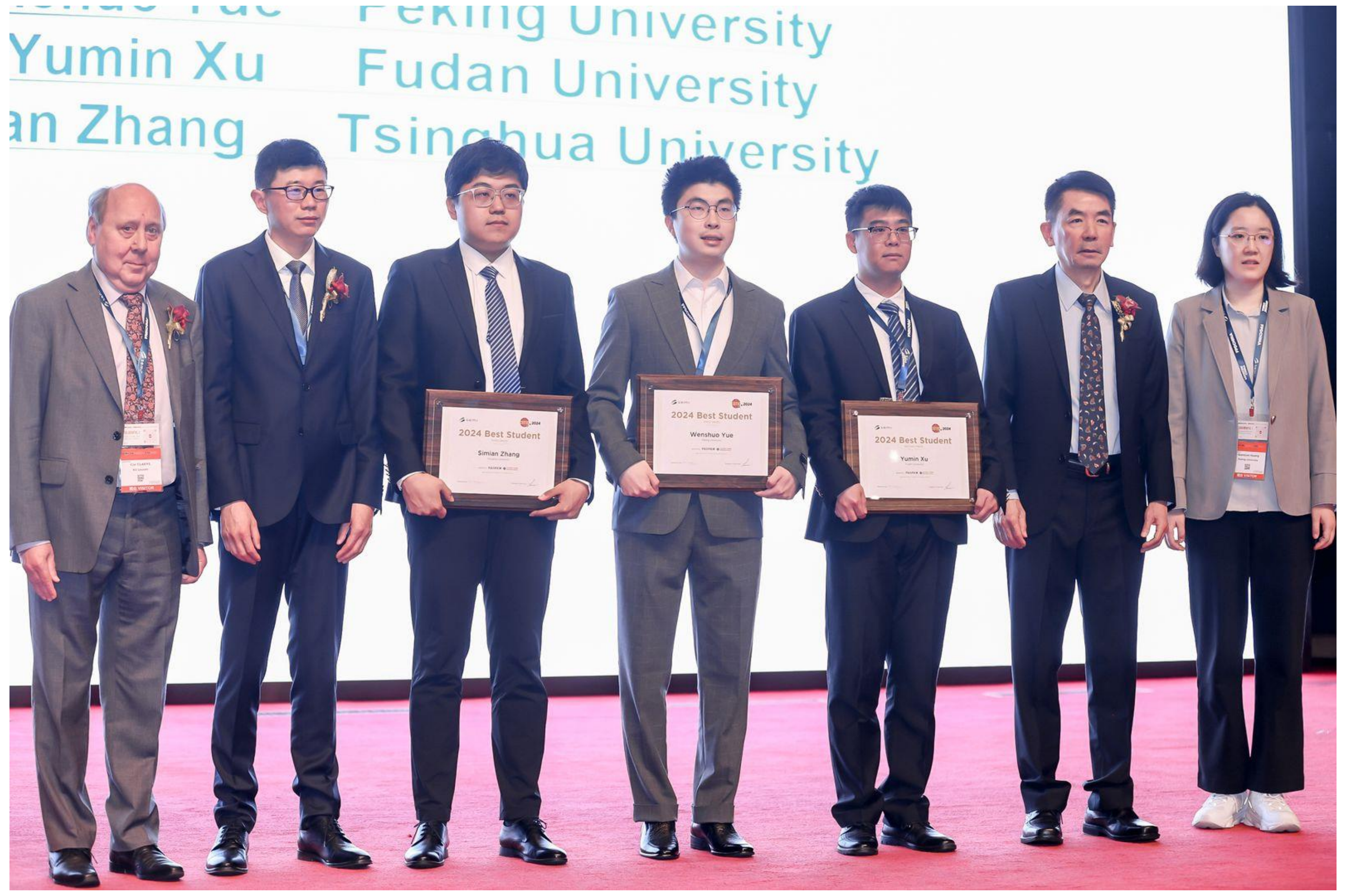
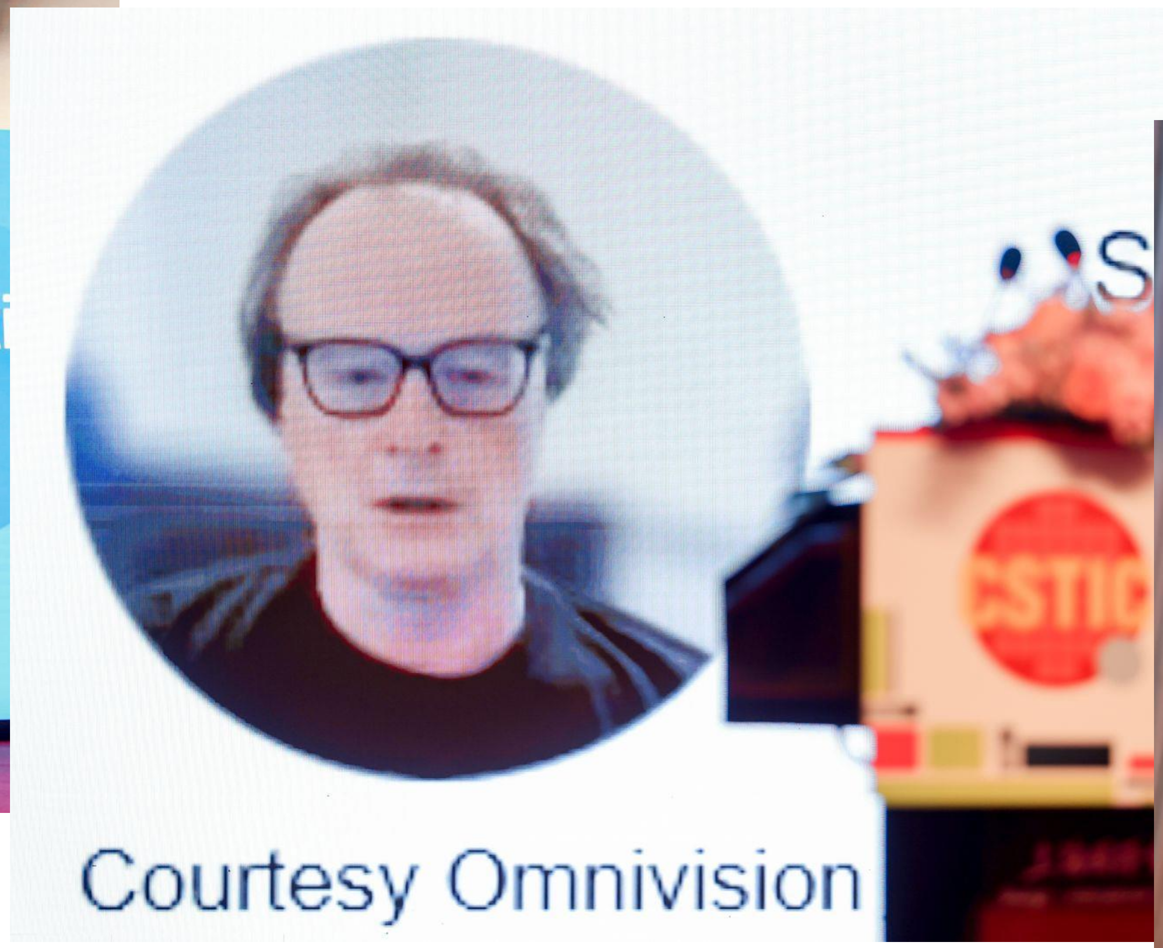
CSTIC 2024 Plenary Session



Plenary Speakers


Courtesy Omnivision

- Evolution of Moore's Law: a Perspective

Dr. Peng Bai, CEO, Rong Semiconductor, China

- New Materials vs New Geometries in Electronic Devices

Prof. John Robertson, Emeritus Professor of Electronic Engineering, Cambridge University, UK

- Integrated Module Approach to Solutions in the Specialty Device Market

Dr. Michael Chudzik, VP of Technology, IMS ICAPS & Packaging, Applied Materials, USA

- 50 Years of Silicon Retina History

Prof. Tobias Delbruck, Professor in Neuromorphic Engineering, Institute of Neuroinformatics, Switzerland

- MEMS - Sustainable Technologies for a Sustainable World

Dr. Giorgio Allegato, MEMS Technology R&D Director, MEMS and Sensor Group, STMicroelectronics, Italy

>200 Oral Presentations and >300 Posters

10 Symposia with >100 Invited Speakers

Symp I: Device Engineering and Memory Technology
Symp. II: Lithography and Patterning
Symp. III: Dry &Wet Etch and Cleaning
Symp. IV: Thin Film, Plating and Process Integration
Symp. V: CMP and Post CMP Cleaning
Symp. VI: Metrology, Reliability and Testing
Symp. VII: Packaging and Assembly
Symp. VIII: MEMS, Sensors and Emerging Semiconductor Technologies
Symp. IX: Design and Automation of Circuits and Systems
Symp. X - AI & IC Manufacturing

Virtual Conference: March 27-April 23 v.semi.org.cn/cstic

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Prof. Can Li,
Assistant Professor,
University of Hong Kong

Prof. Han Wang,
Professor,
University of Hong Kong

Dr. Chris Progler,
CTO&VP,
Photronics

Dr. Toru Fujimori,
Senior Expert,
FUJIFILM Corporation

Dr. Zhuo-Jie Wu,
Director,
HFC Semiconductor

Dr. Roy Pinhassi,
Product Marketing Manager,
Nova Ltd

Dr. Xin Ou, Director,
Shanghai Institute of Microsystem
and Information Technology,
CAS

Mr. Ray Saupe,
Senior Researcher &
Project Manager,
Fraunhofer ENAS

Prof. Jiang Xu,
Professor,
Hongkong University of
Science and Technology

Prof. Puneet Gupta,
Professor,
University of California
at Los Angeles

Prof. Shih-Chii Liu,
Professor,
University of Zurich and
ETH Zurich

Prof. Xiangshui Miao,
Professor and the School
Dean of Integrated Circuits,
Huazhong University of
Science and Technology

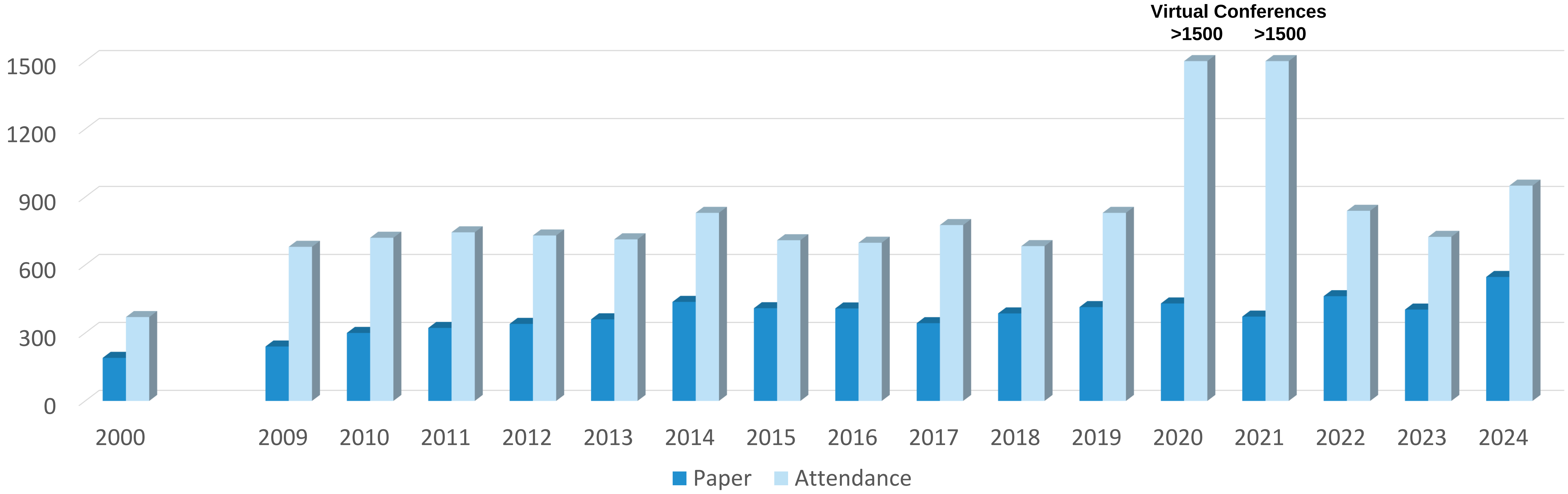
Dr. Juliane Hitzel,
International Business
Development Manager,
Advanced NanoSurface
Technologies(Shenzhen)

Ms. Yali Fu,
Director,
Beijing NAURA Microelectronics Equipment Co., Ltd.

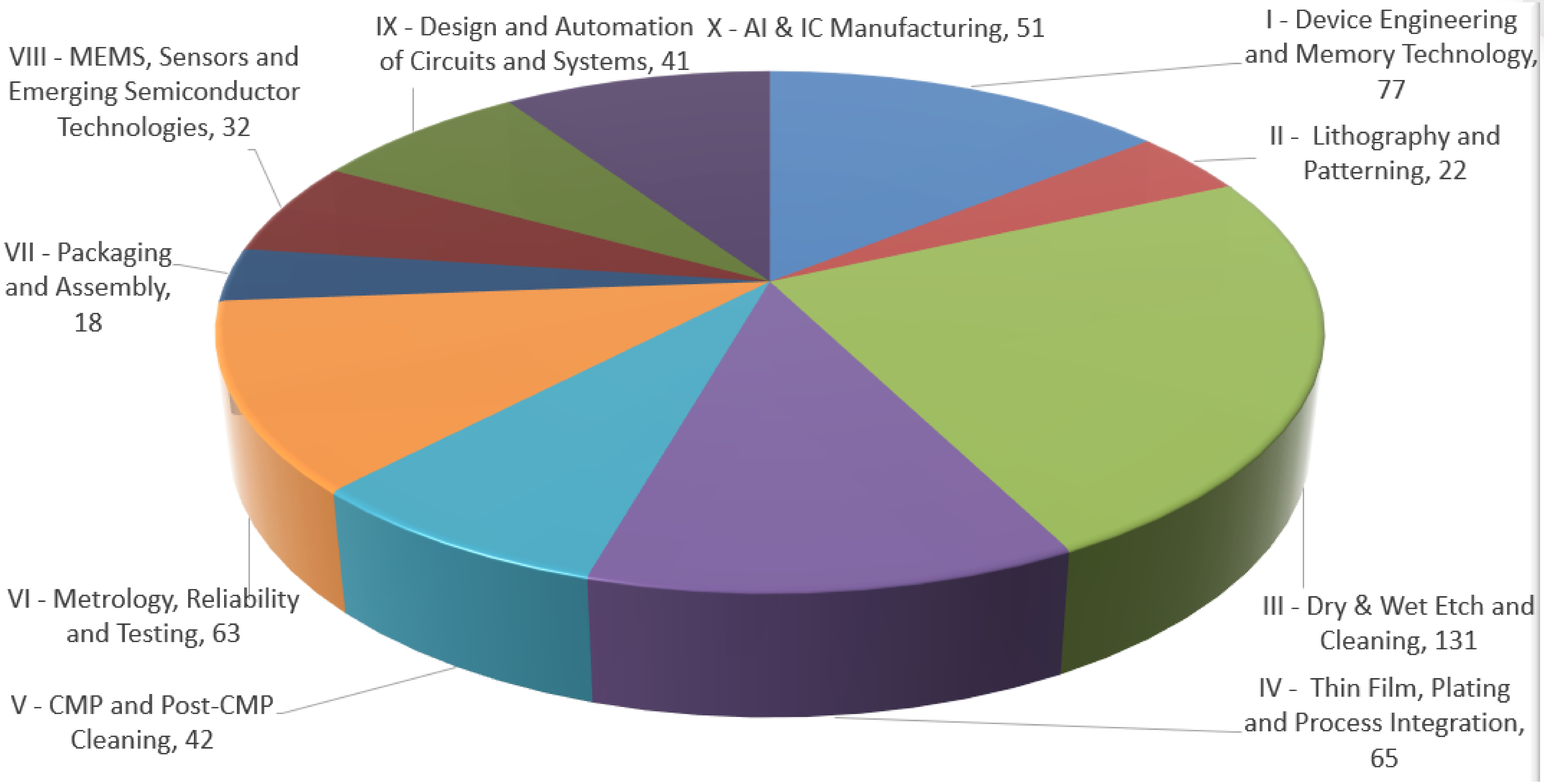
Dr. Terry Wu,
Director,
Samsung Electronics

CSTIC 2024 Summary

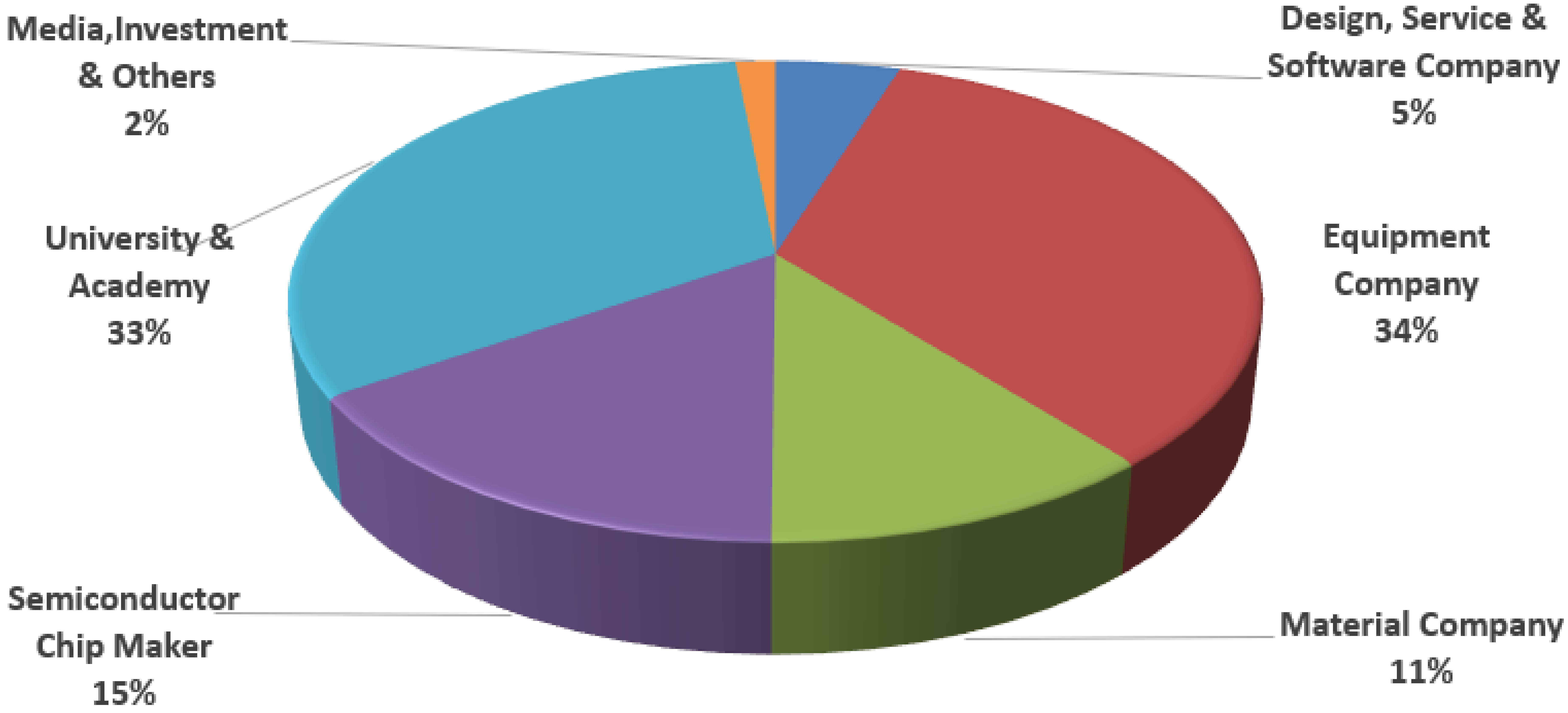
- Largest and most comprehensive, influential annual industrial semiconductor technology conference in China and Asia
- **547 abstracts** have been collected, while **939 registered attendees** joined the onsite conference. Both the numbers **break CSTIC's record.** Speakers and attendees are coming from more than 20 countries and districts, including Belgium, Canada, France, Finland, Germany, Hong Kong China， Israel, Italy, India, Japan, Korea, Malaysia, Netherlands, Sweden, Saudi Arabia, Spain, Singapore, Taiwan China, UK, USA and etc.


Virtual Conferences
>1500 >1500

CSTIC 2024 Symposiums

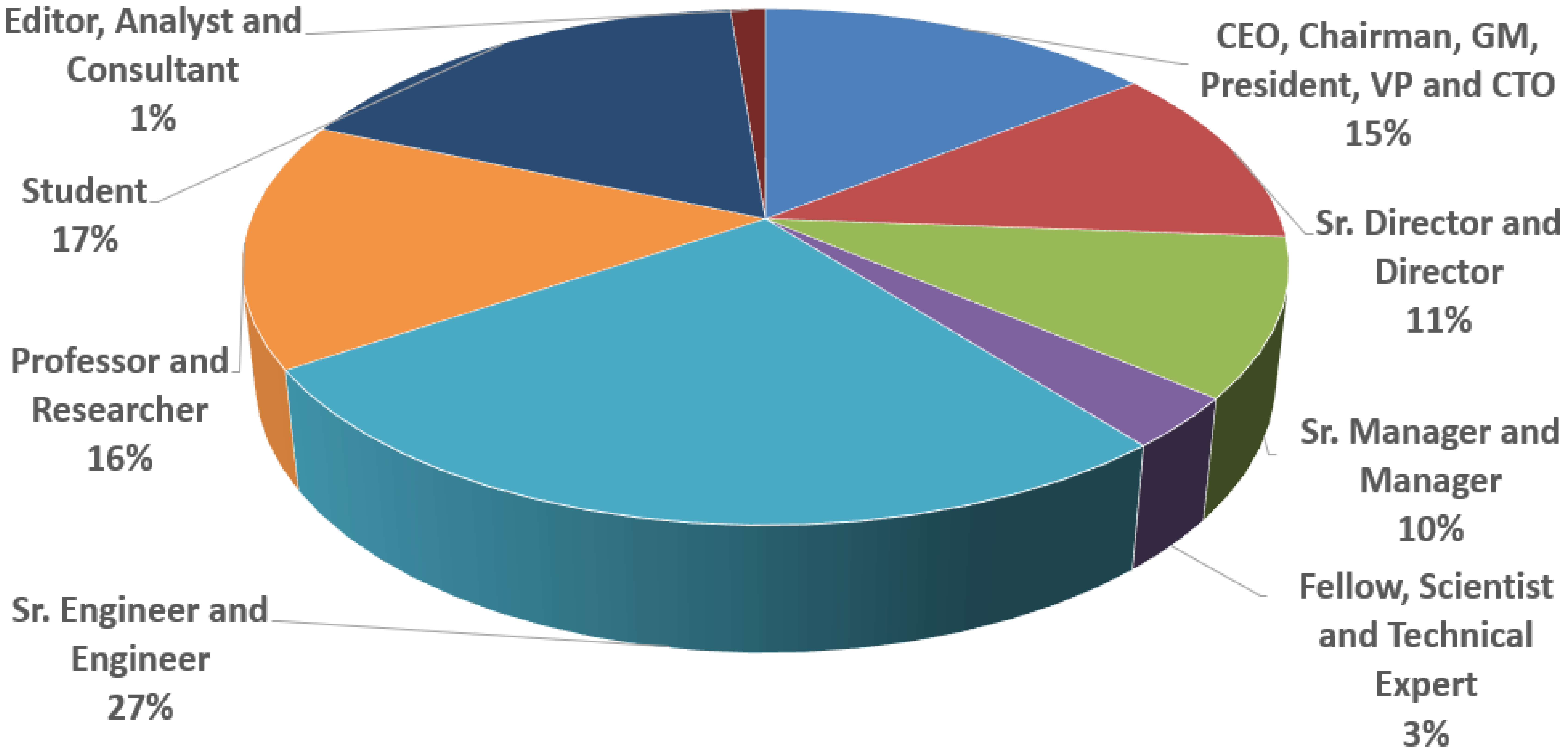


Industry and Academy Cooperation



- 67% attendees from industry, while 33% from universities and institutes

Attendee’s Job Titles



- 26% of the attendees were directors or above, who were the decision makers in companies.

Attendees from 217 Companies, Universities and Institutes

Advantest
Air Liquide
Air Products
AMEC
Anchu Tech
Anhui University
Anji Microelectronics
Applied Materials
ASM
ASML
ASML-Brion
Atlas Copco
Axcelis Technologies,Inc.
Beijing Academy of Quantum Information Sciences
Beijing GAD Semi
Beijing Hekun Business Management
Beijing Integrated Circuit Equipment Innovation Center Co., Ltd
Beijing SAMT
Beijing Shenxing Technology
Beijing SINEVA
Beijng Sevenstar Flow Co.,Ltd.
Beneq
BLACK RIVER(HONG KONG) CO., LIMITED
Broadcom Corporation
Cabot Microelectronics
Caitong Securities
Cambridge University
CAN Semi
CASPA
Central South University
CHINA ELECTRONICS ENGINEERING DESIGN INSTITUTE CO., LTD
China Innovation
City University of Hong Kong
Cordouan Technologies
Corning Incorporated
CUMEC
D2S Inc.
Dalian University of Technology
DISCO
Dow Dupont
E Fund Management
East China Normal University
Eastern Institute of Technology, Ningbo
Edwards Vacuum
Embassy of Canada
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GrandiT Co. Ltd
Guangdong University of Technology
Hangzhou Zhihe Technology
Haohua Gas
Harbin Institute of Technology
Hebei University of Technology
Hefei Institutes of Physical Science, Chinese Academy of Sciences
Hefei National Laboratory for Physical Science at the Microscale
Hesait Technology
HFC Semiconductor
HHGrace
HIMC
HiSilicon
Hitachi high-tech
HLMC
Hong Kong Polytechnic University
Hongkong University
Hongkong University of Science and Technology (Guangzhou)
Huawei
Huawei Hong Kong Research Center
Huawei Technologies R&D Belgium
Huazhong University of Science and Technology
Huntsman Corporation
IC League
ICT, CAS
Illinois Tool Works
Indium
INDUSTRIAL BANK
Institute of Microelectronics of the Chinese Academy of Sciences
Institute of Semiconductor, CAS
Intel

Attendees from 217 Companies, Universities and Institutes

IV Technologies
JCET SEMICONDUCTOR
JET TECHNOLOGY
JHICC
Jiangsu Normal University
Jiangsu Shanshui Semiconductor
Jiangsu Superior Ceramics Times Technology Co., Ltd
JSR Electronic Materials (Shanghai)
King Abdullah University of Science & Technology
KLA Corporation
KU Leuven
Kyoto University
Lam Research
Lanzhou University of Technology
Leadmicro
Leuven Instruments
MalvernPanalytical
Mattson Technology
Meminsights （Beijing）
Micron Memory Taiwan
Mito Kogyo CO., LTD
MKT
Mycronic
Nanjing University
Nanjing University of Posts and Telecommunications
Nanjing University of Technology
Nankai University
National Central University
NATIONAL CENTRAL UNIVERSITY
National University of Defense Technology
NAURA
Nexchip
NI (part of Emerson)
Ningbo Inventech
Ningbo University
Northeast Normal University
NOVA LTD
NXP Semiconductors
OMT ORIGIN MATERIALS TECHNOLOGY
Peking University
Peng Cheng Laboratory
Pingan Investment
PIOTECH
Politecnico di Milano
Polytechnical Univ. Madrid (UPM)
Pusan National University
Qianmo Micros Design LLC
Qingdao Haicun Microelectronics
Qualcomm
Reliance Memory
Rong Semiconductor, China
Ruikang Intelligent (Shenzhen)
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Shanghai Institute of Microsystem and Information Technology (SIMIT)
Shanghai Jiao Tong University
Shanghai Kangbo Chemical
Shanghai LSTD
Shanghai Optoelectronic Technology Innovation Center
Shanghai Tech University
Shanghai University
Shanghai University of Technology
Shanghai VF Semiconductor
Shanxi University
Shengzhen Pango Micro
Shenzhen Angstrom Excellence Technology
Shenzhen DGT Co. , Ltd.
Shenzhen Reexen Technology
Shenzhen Sicarrier Technology
Shenzhen University
Siemens
SiEn(Qingdao) Integrated Circuites
SIMIC Captial
SIMM Tech
SMEE
SMIC
SMNC
South University of Science and Technology
Southeast University
Spectron Tech/UIUC
STMicroelectronics
STR Software
Sunshi Technology
Suzhou FISCHERTECH
Suzhou Laboratory
Suzhou Runbang semiconductor material technology
Technische Universiteit Delft
T-Head
Tokyo Electron
Toray Advanced Materials Research Laboratories(China)Co.,Ltd.
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UniversiteitLeiden
University of California, Los Angeles
University of Chinese Academy of Sciences
University of Science and Technology of China
UPM
VAT
Veerabhadra Mining and Minerals
Witmem
Wuxi Huaying Micro
X-FAB
Xiamen industrial Technology Research Institute
Xian ESWINSI
Xian Unisemi
Yuan-Ze University
Zeiss
Zhangjiang National Laboratory
Zhejiang Lab
Zhejiang University
Zhizhen Storage (Beijing) Technology Co., Ltd
Zhongtian Huifu Industrial Investment
ZJU-Hangzhou Global Scientific and Technological Innovation Center

WFD Training Courses and Panel Discussion

Panel Discussion:
AI for IC Design & Manufacturing: The Hopes, Challenges, and Opportunities
Moderator: **Prof. Cheng Zhuo, Zhejiang University**
Panelists: **Prof. Daniele Ielmini, Politecnico Di Milano**
Dr. Jun Yuan, Qualcomm
Prof. Yu Wang, Tsinghua University
Prof. Runsheng Wang, Peking University
Mr. Zusheng Yang, Empyrean

WFD Tutorial: MEMS Enabled Liquid Biopsy
Speaker: **Prof. Wei Wang**
Deputy Dean of School of Integrated Circuits, Peking University;
Director of the National Key Laboratory of Advanced Micro and Nano Manufacture Technology.

WFD Tutorial: Thin Film Deposition for IC Processing Technology
Speaker: **Dr. Chao Zhao**
Senior VP of Beijing Superstring Academy of Memory Technology (SAMT), China

Attendees to Plenary Session and 10 Symposia

CSTIC Attendee Number	2024	2023
Conference	939	684
Plenary Session	685	549
Symposium I: Device Engineering and Memory Technology	276	250
Symposium II: Lithography and Patterning	174	235
Symposium III: Dry & Wet Etch and Cleaning	326	314
Symposium IV: Thin Film, Plating and Process Integration	361	389
Symposium V: CMP and Post-CMP Cleaning	238	157
Symposium VI: Metrology, Reliability and Testing	183	143
Symposium VII: Packaging and Assembly	142	77
Symposium VIII:MEMS, Sensors and Emerging Semiconductor Technologies	129	52
Symposium IX: Design and Automation of Circuits and Systems	153	129
Sympsium X: AI & IC Manufacturing	181	
Symp II &III Joint Session	172	199
Panel Discussion	77	

**Symposium I-X attendee number was Day 1 and Day 2 in total*

Conference Executive Committees

Dr. Beichao Zhang
Conference Chair
VP of Hangzhou HFC, China

Prof. Bin Yu
Conference Executive Co-Chair Symp-X Chair Professor, Zhejiang University, China

Dr. Ru Huang
Conference Co-Chair Symp-I Chair Professor of Peking University, President of Southeast University, Academician of Chinese Academy of Sciences

Dr. Cor Claeys
Conference Co-Chair and Award Selection Chair Professor, KU Leuven, Belgium

Dr. Linyong (Leo) Pang
Symp-II Chair
Vice President, D2S Inc., USA

Dr. Ying Zhang
Symp-III Chair
Consultant

Dr. Xiaoping Shi
Symp-IV Chair
CTO, Beijing Naura Microelectronics, China

Dr. Xinping Qu
Symp-V Chair
Professor, Fudan University, China

Dr. Xiaowei Li
Symp-VI Chair
Deputy Director, ICT, CAS, China

Dr. Steve X. Liang
Symp-VII Chair

Prof. Jianshi Tang (acting)
Symp-VIII Chair Associate Professor, Tsinghua University, China

Prof. Weikang Qian
Symp-IX Chair
Assistant Professor , University of Michigan-Shanghai Jiao Tong University Joint Institute, China

Dr. Hsiang-Lan Lung
Poster Chair
Director, MXIC, Taiwan, China

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CSTIC 2025 Call for Papers

Time: March 24 ~ 25, 2025

CSTIC 2025 call for papers and manuscript deadlines:

Abstract Due: Sep. 30, 2024
Author Notification: Oct. 15, 2024
Manuscript Due: Dec. 15, 2024

Copyright Due: Feb. 10, 2025
Presentation Due: Feb. 20, 2025
Conference Date: Mar. 24-25, 2025

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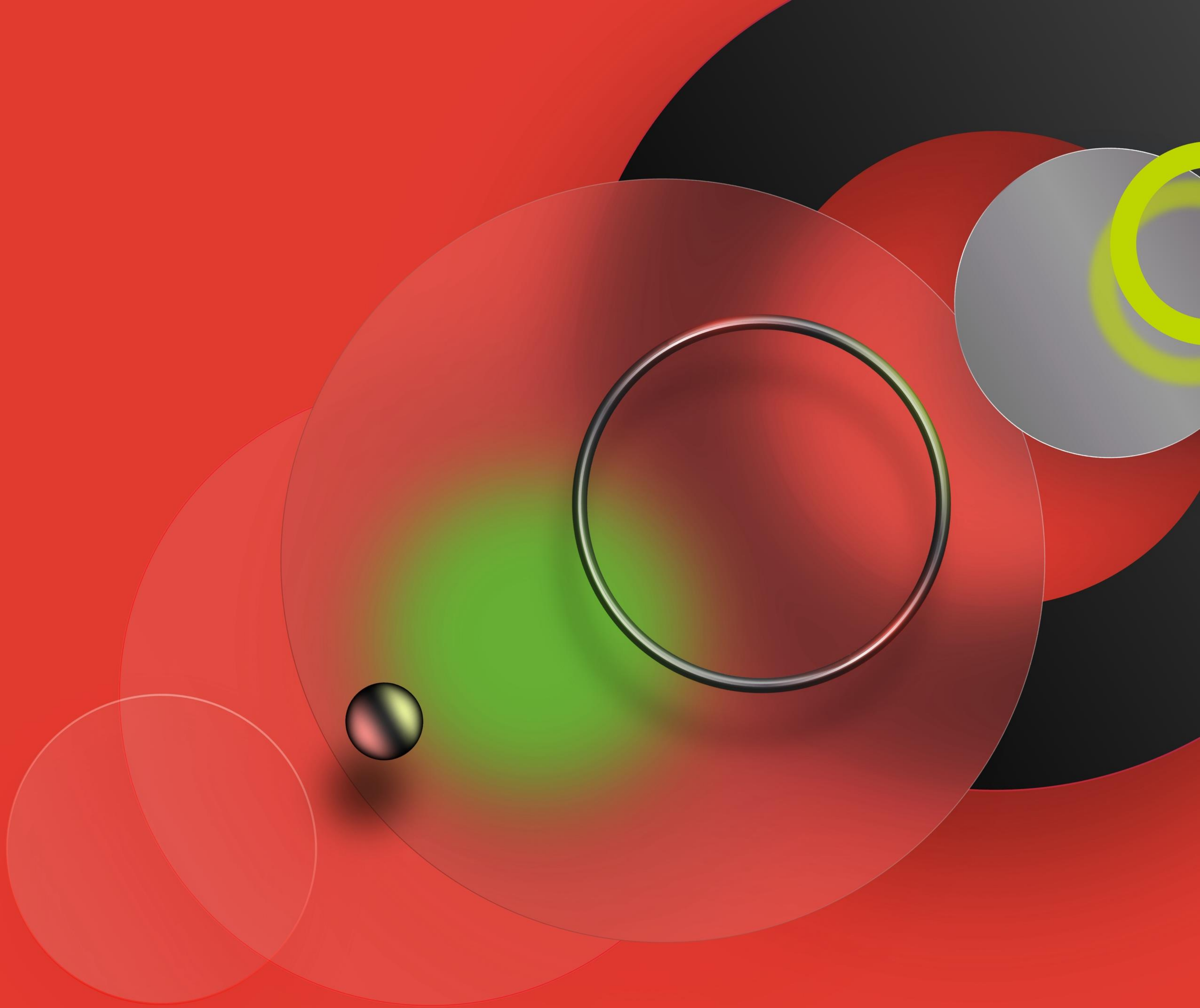
Thank you！



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